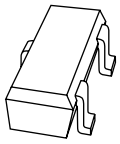

PDTC323TK

NPN 500 mA, 15 V resistor-equipped transistor; R1 = 2.2 kΩ, R2 = open

Rev. 02 — 16 November 2009 Product data sheet

1. Product profile

1.1 General description

500 mA NPN Resistor-Equipped Transistor (RET) in a small SOT346 (SC-59A) SMD plastic package.

PNP complement: PDTA323TK.

1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- 500 mA output current capability
- Reduces component count
- Reduces pick and place costs

1.3 Applications

- Digital application in automotive and industrial segments
- Controlling IC inputs
- Cost saving alternative for BC817 series in digital applications
- Switching loads

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	15	V
I_O	output current		-	-	500	mA
R1	bias resistor 1 (input)		1.54	2.2	2.86	kΩ

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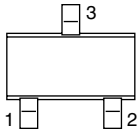
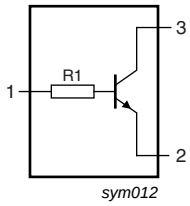
2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	input (base)		
2	GND (emitter)		
3	output (collector)		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PDTC323TK	SC-59A	plastic surface mounted package; 3 leads	SOT346

4. Marking

Table 4. Marking codes

Type number	Marking code
PDTC323TK	57

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	30	V
V_{CEO}	collector-emitter voltage	open base		-	15	V
V_{EBO}	emitter-base voltage	open collector		-	5	V
V_I	input voltage					
	positive			-	+12	V
	negative			-	–5	V
I_O	output current			-	500	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	250	mW
T_{stg}	storage temperature			–65	+150	°C
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			–65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

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6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	500	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 7. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	V_{CB} = 30 V; I_E = 0 A	-	-	100	nA
I_{CEO}	collector-emitter cut-off current	V_{CE} = 15 V; I_B = 0 A	-	-	0.5	µA
I_{EBO}	emitter-base cut-off current	V_{EB} = 5 V; I_C = 0 A	-	-	100	nA
h_{FE}	DC current gain	V_{CE} = 5 V; I_C = 50 mA	100	300	-	
V_{CEsat}	collector-emitter saturation voltage	I_C = 50 mA; I_B = 2.5 mA	-	25	80	V
R1	bias resistor 1 (input)		1.54	2.2	2.86	kΩ
C_c	collector capacitance	V_{CB} = 10 V; $I_E = i_e$ = 0 A; f = 1 MHz	-	7	-	pF

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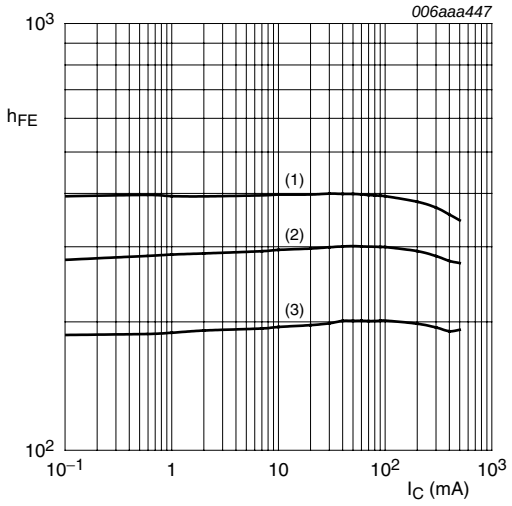


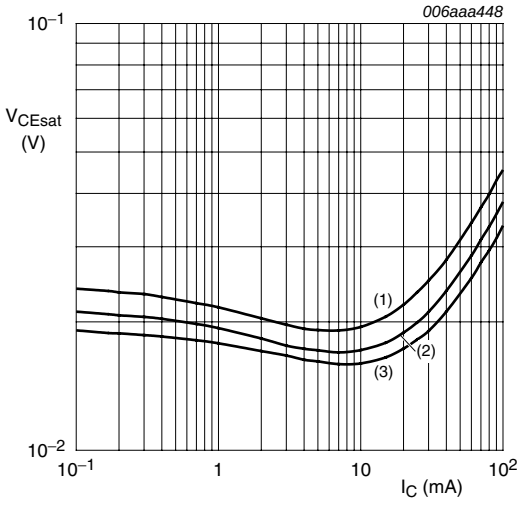
V_{CE} = 5 V

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −40 °C

Fig 1. DC current gain as a function of collector current; typical values



I_C/I_B = 20

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −40 °C

Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values

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8. Package outline

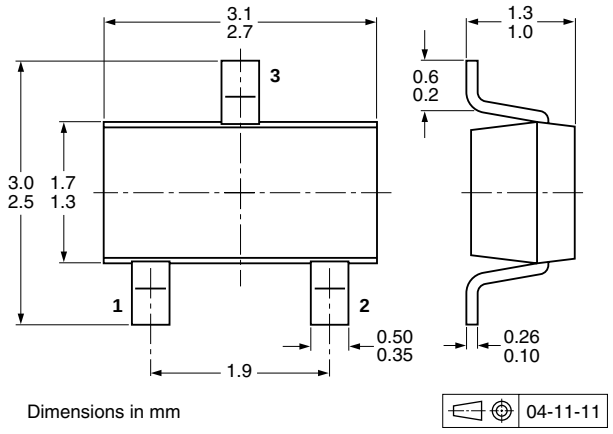

Fig 3. Package outline SOT346 (SC-59A/TO-236)

9. Packing information

Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description	Packing quantity	
			3000	10000
PDTC323TK	SOT346	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see Section 12.

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10. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PDTC323TK_2	20091116	Product data sheet	-	PDTC323TK_1
Modifications:	• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.			
PDTC323TK_1	20050603	Product data sheet	-	-

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11. Legal information

11.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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13. Contents

1	**Product profile**	**1**
1.1	General description	1
1.2	Features	1
1.3	Applications	1
1.4	Quick reference data	1
2	**Pinning information**	**2**
3	**Ordering information**	**2**
4	**Marking**	**2**
5	**Limiting values**	**2**
6	**Thermal characteristics**	**3**
7	**Characteristics**	**3**
8	**Package outline**	**5**
9	**Packing information**	**5**
10	**Revision history**	**6**
11	**Legal information**	**7**
11.1	Data sheet status	7
11.2	Definitions	7
11.3	Disclaimers	7
11.4	Trademarks	7
12	**Contact information**	**7**
13	**Contents**	**8**

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